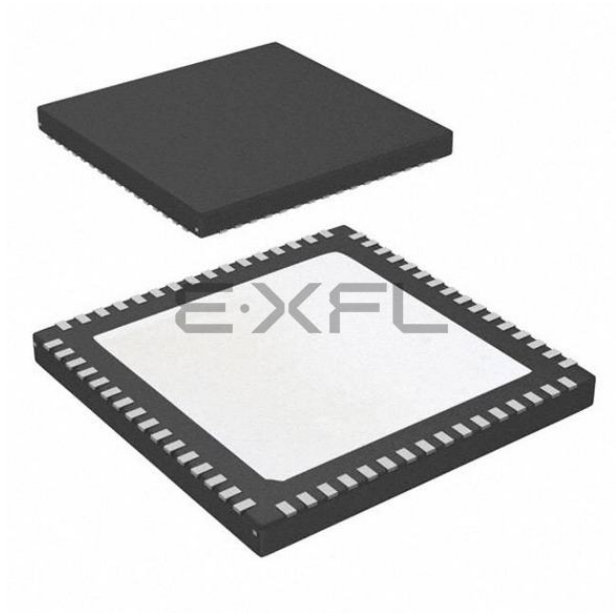
Renesas Electronics America Inc - R5F52317BDND#U0 Datasheet



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Applications of "Embedded - Microcontrollers"

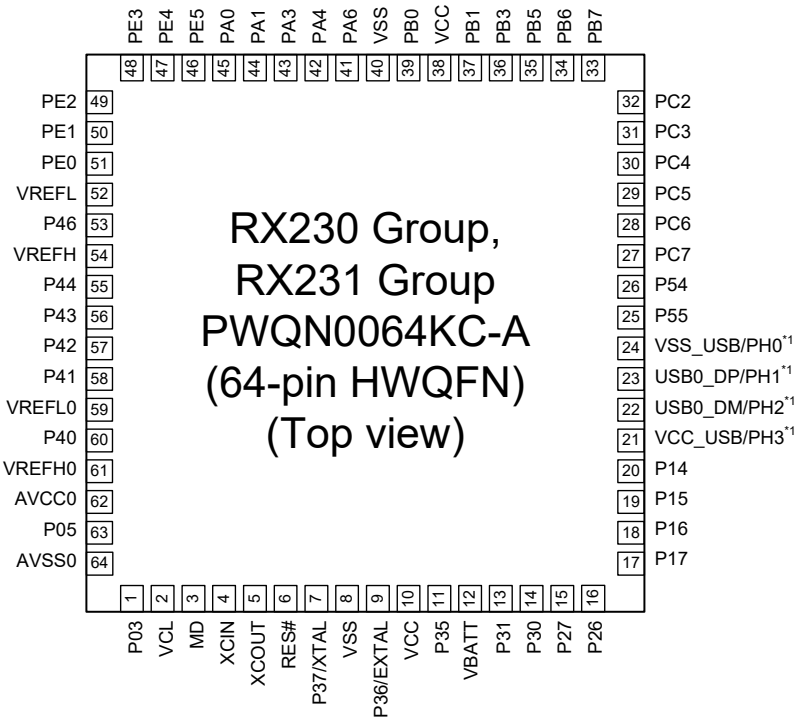
Details	
Product Status	Not For New Designs
Core Processor	RXv2
Core Size	32-Bit Single-Core
Speed	54MHz
Connectivity	CANbus, I²C, IrDA, SCI, SD/SDIO, SPI, SSI, USB OTG
Peripherals	DMA, LVD, POR, PWM, WDT
Number of I/O	43
Program Memory Size	384KB (384K x 8)
Program Memory Type	FLASH
EEPROM Size	8K x 8
RAM Size	64K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 5.5V
Data Converters	A/D 12x12b; D/A 2x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-WFQFN Exposed Pad
Supplier Device Package	64-HWQFN (9x9)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f52317bdnd-u0

Table 1.1 Outline of Specifications (2/4)

Classification	Module/Function	Description
Low power consumption	Low power consumption functions	• Module stop function • Three low power consumption modes Sleep mode, deep sleep mode, and software standby mode • Low power timer that operates during the software standby state
	Function for lower operating power consumption	• Operating power control modes High-speed operating mode, middle-speed operating mode, and low-speed operating mode
Interrupt	Interrupt controller (ICUb)	• Interrupt vectors: 167 • External interrupts: 9 (NMI, IRQ0 to IRQ7 pins) • Non-maskable interrupts: 7 (NMI pin, oscillation stop detection interrupt, voltage monitoring 1 interrupt, voltage monitoring 2 interrupt, WDT interrupt, IWDT interrupt, and VBATT power monitoring interrupt) • 16 levels specifiable for the order of priority
External bus extension		• The external address space can be divided into four areas (CS0 to CS3), each with independent control of access settings. Capacity of each area: 16 Mbytes (CS0 to CS3) A chip-select signal (CS0# to CS3#) can be output for each area. Each area is specifiable as an 8-bit or 16-bit bus space The data arrangement in each area is selectable as little or big endian (only for data). Bus format: Separate bus, multiplex bus • Wait control • Write buffer facility
DMA	DMA controller (DMACA)	• 4 channels • Three transfer modes: Normal transfer, repeat transfer, and block transfer • Activation sources: Software trigger, external interrupts, and interrupt requests from peripheral functions
	Data transfer controller (DTCa)	• Transfer modes: Normal transfer, repeat transfer, and block transfer • Activation sources: Interrupts • Chain transfer function
I/O ports	General I/O ports	100-pin/64-pin/48-pin I/O: 79/43/30 (RX231 Group), 83/47/34 (RX230 Group) • Input: 1/1/1 Pull-up resistors: 79/43/30(RX231 Group), 83/47/34 (RX230 Group) • Open-drain outputs: 58/34/26 • 5-V tolerance: 8/5/5
Event link controller (ELC)		• Event signals of 61 types can be directly connected to the module • Operations of timer modules are selectable at event input • Capable of event link operation for port B and port E
Multi-function pin controller (MPC)		Capable of selecting the input/output function from multiple pins
Timers	16-bit timer pulse unit (TPUa)	• (16 bits × 6 channels) × 1 unit • Maximum of 16 pulse-input/output possible • Select from among seven or eight counter-input clock signals for each channel • Supports the input capture/output compare function • Output of PWM waveforms in up to 15 phases in PWM mode • Support for buffered operation, phase-counting mode (two-phase encoder input) and cascade connected operation (32 bits × 2 channels) depending on the channel. • Capable of generating conversion start triggers for the A/D converters • Signals from the input capture pins are input via a digital filter • Clock frequency measuring method
	Multi-function timer pulse unit 2 (MTU2a)	• (16 bits × 6 channels) × 1 unit • Up to 16 pulse-input/output lines and three pulse-input lines are available based on the six 16-bit timer channels • Select from among eight or seven counter-input clock signals for each channel (PCLK/1, PCLK/4, PCLK/16, PCLK/64, PCLK/256, PCLK/1024, MTCLKA, MTCLKB, MTCLKC, MTCLKD) other than channel 5, for which only four signals are available. • Input capture function • 21 output compare/input capture registers • Pulse output mode • Complementary PWM output mode • Reset synchronous PWM mode • Phase-counting mode • Capable of generating conversion start triggers for the A/D converter
	Port output enable 2 (POE2a)	Controls the high-impedance state of the MTU's waveform output pins
	Compare match timer (CMT)	• (16 bits × 2 channels) × 2 units • Select from among four clock signals (PCLK/8, PCLK/32, PCLK/128, PCLK/512)
	Watchdog timer (WDTA)	• 14 bits x 1 channel • Select from among six counter-input clock signals (PCLK/4, PCLK/64, PCLK/128, PCLK/512, PCLK/2048, PCLK/8192)

Table 1.3 List of Products: D Version (T_a = –40 to +85°C) (2/2)

Group	Part No.	Order Part No.	Package	ROM Capacity	RAM Capacity	E2 DataFlash	Operating Frequency	Security Function	SDHI	CAN	Operating Temperature
RX231	R5F52316ADFL	R5F52316ADFL#30	PLQP0048KB-B	256 Kbytes	32 Kbytes	8 Kbytes	54 MHz	Not available	Not available	Available	–40 to +85°C
	R5F52316CDFL	R5F52316CDFL#30						Not available	Not available	Not available	
	R5F52315ADLA	R5F52315ADLA#20	PTLG0100KA-A	128 Kbytes	32 Kbytes	8 Kbytes	54 MHz	Not available	Not available	Available	–40 to +85°C
	R5F52315CDLA	R5F52315CDLA#20						Not available	Not available	Not available	
	R5F52315ADFP	R5F52315ADFP#30	PLQP0100KB-B					Not available	Not available	Available	
	R5F52315CDFP	R5F52315CDFP#30						Not available	Not available	Not available	
	R5F52315CDLF	R5F52315CDLF#20	PWLG0064KA-A					Not available	Not available	Not available	
	R5F52315ADND	R5F52315ADND#U0	PWQN0064KC-A					Not available	Not available	Available	
	R5F52315CDND	R5F52315CDND#U0						Not available	Not available	Not available	
	R5F52315ADFM	R5F52315ADFM#30	PLQP0064KB-C					Not available	Not available	Available	
	R5F52315CDFM	R5F52315CDFM#30						Not available	Not available	Not available	
	R5F52315ADNE	R5F52315ADNE#U0	PWQN0048KB-A					Not available	Not available	Available	
	R5F52315CDNE	R5F52315CDNE#U0						Not available	Not available	Not available	
	R5F52315ADFL	R5F52315ADFL#30	PLQP0048KB-B					Not available	Not available	Available	
	R5F52315CDFL	R5F52315CDFL#30						Not available	Not available	Not available	
RX230	R5F52306ADLA	R5F52306ADLA#20	PTLG0100KA-A	256 Kbytes	32 Kbytes	8 Kbytes	54 MHz	Not available	Not available	Not available	–40 to +85°C
	R5F52306ADFP	R5F52306ADFP#30	PLQP0100KB-B					Not available	Not available	Not available	
	R5F52306ADLF	R5F52306ADLF#20	PWLG0064KA-A					Not available	Not available	Not available	
	R5F52306ADND	R5F52306ADND#U0	PWQN0064KC-A					Not available	Not available	Not available	
	R5F52306ADFM	R5F52306ADFM#30	PLQP0064KB-C					Not available	Not available	Not available	
	R5F52306ADNE	R5F52306ADNE#U0	PWQN0048KB-A					Not available	Not available	Not available	
	R5F52306ADFL	R5F52306ADFL#30	PLQP0048KB-B					Not available	Not available	Not available	
	R5F52305ADLA	R5F52305ADLA#20	PTLG0100KA-A	128 Kbytes				Not available	Not available	Not available	
	R5F52305ADFP	R5F52305ADFP#30	PLQP0100KB-B					Not available	Not available	Not available	
	R5F52305ADLF	R5F52305ADLF#20	PWLG0064KA-A					Not available	Not available	Not available	
	R5F52305ADND	R5F52305ADND#U0	PWQN0064KC-A					Not available	Not available	Not available	
	R5F52305ADFM	R5F52305ADFM#30	PLQP0064KB-C					Not available	Not available	Not available	
	R5F52305ADNE	R5F52305ADNE#U0	PWQN0048KB-A					Not available	Not available	Not available	
	R5F52305ADFL	R5F52305ADFL#30	PLQP0048KB-B					Not available	Not available	Not available	



Note: This figure indicates the power supply pins and I/O port pins.
For the pin configuration, see the table “List of Pins and Pin Functions (64-Pin LFQFP/HWQFN)”.
Note: It is recommended to connect an exposed die pad to VSS.

Note 1. RX230: PH0, PH1, PH2, PH3
RX231: VSS_USB, USB0_DP, USB0_DM, VCC_USB

Figure 1.6 Pin Assignments of the 64-Pin HWQFN

Table 1.7 List of Pins and Pin Functions (100-Pin LFQFP) (2/3)

Pin No.	Power Supply, Clock, System Control	I/O Port	External Bus	Timers (MTU, TPU, TMR, RTC, CMT, POE, CAC)	Communications (SCI, RSPI, RIIC, RSCAN, USB, SSI)	Memory Interface (SDHI)	Touch sensing	Others
42		P52	RD#				TS18	
43		P51	WR1#/BC1#/ WAIT#				TS19	
44		P50	WR0#/WR#				TS20	
45	UB	PC7	A23/CS0#	MTIOC3A/MTCLKB/TMO2	TXD8/SMOSI8/SSDA8/ MISOA			CACREF
46		PC6	A22/CS1#	MTIOC3C/MTCLKA/TMCI2	RXD8/SMISO8/SSCL8/ MOSIA		TS22	
47		PC5	A21/CS2#/ WAIT#	MTIOC3B/MTCLKD/TMRI2	SCK8/RSPCKA		TS23	
48		PC4	A20/CS3#	MTIOC3D/MTCLKC/TMCI1/ POE0#	SCK5/CTS8#/RTS8#/ SS8#/SSLA0	SDHI_D1	TSCAP	
49		PC3	A19	MTIOC4D/TCLKB	TXD5/SMOSI5/SSDA5/ IRTXD5	SDHI_D0	TS27	
50		PC2	A18	MTIOC4B/TCLKA	RXD5/SMISO5/SSCL5/ SSLA3/ IRRXD5	SDHI_D3	TS30	
51		PC1	A17	MTIOC3A/TCLKD	SCK5/SSLA2		TS33	
52		PC0	A16	MTIOC3C/TCLKC	CTS5#/RTS5#/SS5#/ SSLA1		TS35	
53		PB7	A15	MTIOC3B/TIOCB5	TXD9/SMOSI9/SSDA9	SDHI_D2		
54		PB6	A14	MTIOC3D/TIOCA5	RXD9/SMISO9/SSCL9	SDHI_D1		
55		PB5	A13	MTIOC2A/MTIOC1B/ TMRI1/POE1#/TIOCB4	SCK9/USB0_VBUS	SDHI_CD		
56		PB4	A12	TIOCA4	CTS9#/RTS9#/SS9#			
57		PB3	A11	MTIOC0A/MTIOC4A/TMO0/ POE3#/TIOCD3/TCLKD	SCK6	SDHI_WP		
58		PB2	A10	TIOCC3/TCLKC	CTS6#/RTS6#/SS6#			
59		PB1	A9	MTIOC0C/MTIOC4C/ TMCI0/TIOCB3	TXD6/SMOSI6/SSDA6	SDHI_CLK		IRQ4/ CMPOB1
60	VCC							
61		PB0	A8	MTIC5W/TIOCA3	RXD6/SMISO6/SSCL6/ RSPCKA	SDHI_CMD		
62	VSS							
63		PA7	A7	TIOCB2	MISOA			
64		PA6	A6	MTIC5V/MTCLKB/TMCI3/ POE2#/TIOCA2	CTS5#/RTS5#/SS5#/ MOSIA/SSIWS0			
65		PA5	A5	TIOCB1	RSPCKA			
66		PA4	A4	MTIC5U/MTCLKA/TMRI0/ TIOCA1	TXD5/SMOSI5/SSDA5/ SSLA0/SSITXD0/IRTXD5			IRQ5 / CVREFB1
67		PA3	A3	MTIOC0D/MTCLKD/ TIOCD0/TCLKB	RXD5/SMISO5/SSCL5/ SSIRXD0/IRRXD5			IRQ6 /CMPB1
68		PA2	A2		RXD5/SMISO5/SSCL5/ SSLA3/IRRXD5			
69		PA1	A1	MTIOC0B/MTCLKC/ TIOCB0	SCK5/SSLA2/SSISCK0			
70		PA0	A0/BC0#	MTIOC4A/TIOCA0	SSLA1			CACREF
71		PE7	D15[A15/D15]					IRQ7/AN023
72		PE6	D14[A14/D14]					IRQ6/AN022
73		PE5	D13[A13/D13]	MTIOC4C/MTIOC2B				IRQ5/AN021/ CMPOB0
74		PE4	D12[A12/D12]	MTIOC4D/MTIOC1A				AN020/ CMPA2/ CLKOUT
75		PE3	D11[A11/D11]	MTIOC4B/POE8#	CTS12#/RTS12#/SS12#/ AUDIO_MCLK			AN019/ CLKOUT
76		PE2	D10[A10/D10]	MTIOC4A	RXD12/RXDX12/ SMISO12/SSCL12			IRQ7/AN018/ CVREFB0
77		PE1	D9[A9/D9]	MTIOC4C	TXD12/TXDX12/SIOX12/ SMOSI12/SSDA12			AN017/ CMPB0
78		PE0	D8[A8/D8]		SCK12			AN016

Table 1.8 List of Pins and Pin Functions (64-Pin WFLGA) (1/2)

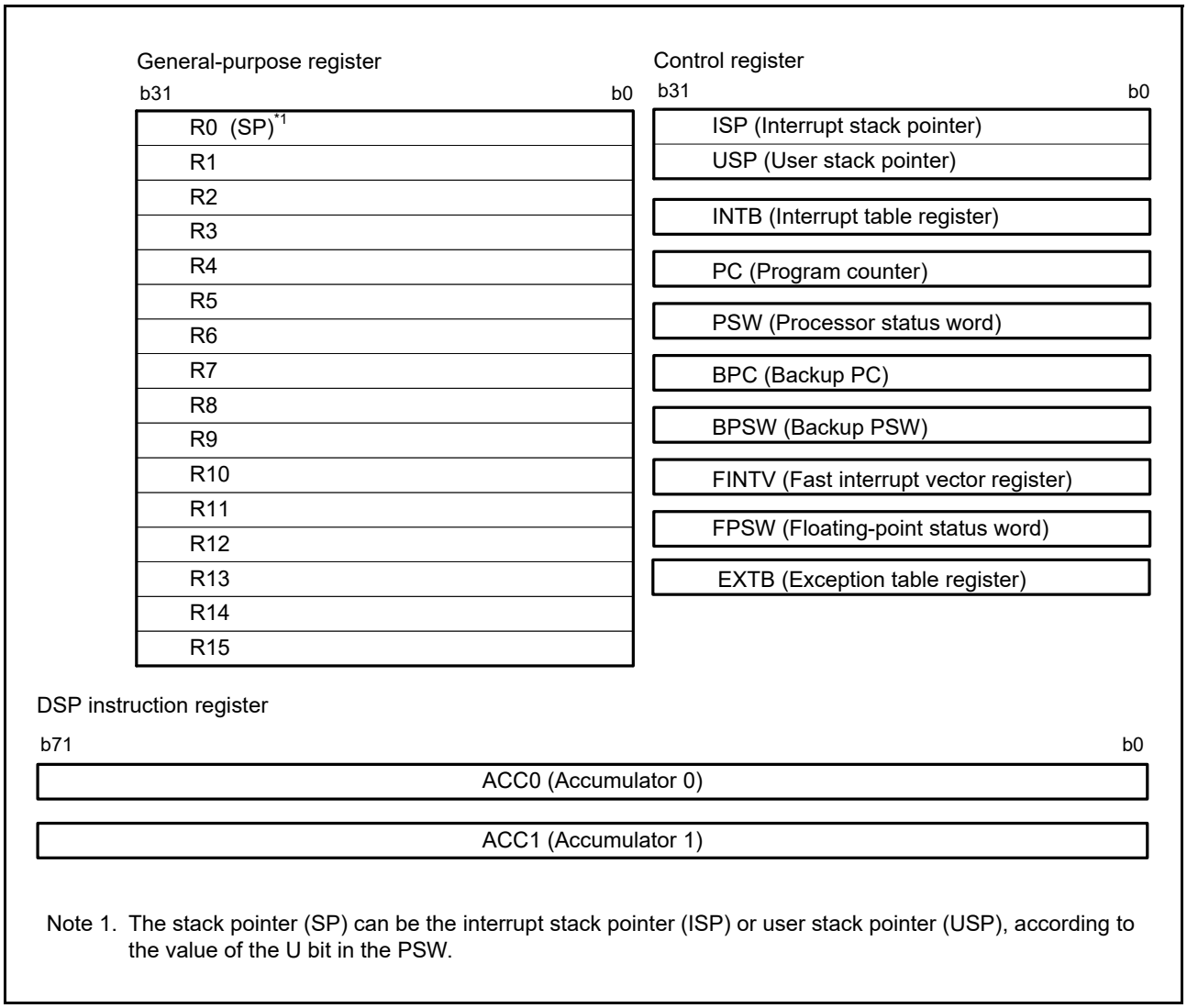
Pin No.	Power Supply, Clock, System Control	I/O Port	Timers (MTU, TPU, TMR, RTC, CMT, POE, CAC)	Communications (SCI, RSPI, RIIC, RSCAN, USB, SSI)	Memory Interface (SDHI)	Touch sensing	Others
A1		P05					DA1
A2	AVCC0						
A3	VREFH0						
A4	VREFL0						
A5	VREFH						
A6	VREFL						
A7		PE2	MTIOC4A	RXD12/RXDX12/SMISO12/ SSCL12			IRQ7/AN018/ CVREFB0
A8		PE3	MTIOC4B/POE8#	CTS12#/RTS12#/SS12#/ AUDIO_MCLK			AN019/CLKOUT
B1	VCL						
B2	AVSS0						
B3		P40					AN000
B4		P42					AN002
B5		P44					AN004
B6		P46					AN006
B7		PE1	MTIOC4C	TXD12/TXDX12/SIOX12/ SMOSI12/SSDA12			AN017/CMPB0
B8		PE4	MTIOC4D/MTIOC1A				AN020/CMPA2/ CLKOUT
C1	XCIN						
C2	MD						FINED
C3		P03					DA0
C4		P41					AN001
C5		P43					AN003
C6		PE0		SCK12			AN016
C7		PE5	MTIOC4C/MTIOC2B				IRQ5/AN021/ CMPOB0
C8		PA0	MTIOC4A/TIOCA0	SSLA1			CACREF
D1	XCOUT						
D2	RES#						
D3		P27	MTIOC2B/TMCI3	SCK1/ SSIWS0		TS2	CVREFB3
D4		P14	MTIOC3A/MTCLKA/TMRI2/ TIOCB5/TCLKA	CTS1#/RTS1#/SS1#/CTXD0/ USB0_OVRCURA		TS13	IRQ4/CVREFB2
D5		PA6	MTIC5V/MTCLKB/TMCI3/POE2#/ TIOCA2	CTS5#/RTS5#/SS5#/MOSIA/ SSIWS0			
D6		PA4	MTIC5U/MTCLKA/TMRI0/TIOCA1	TXD5/SMOSI5/SSDA5/SSLA0/ SSITXD0/IRTXD5			IRQ5 /CVREFB1
D7		PA1	MTIOC0B/MTCLKC/TIOCB0	SCK5/SSLA2/SSISCK0			
D8		PA3	MTIOC0D/MTCLKD/TIOCD0/ TCLKB	RXD5/SMISO5/SSCL5/SSIRXD0/ IRRXD5			IRQ6 /CMPB1
E1	VSS						
E2	VBATT						
E3		P30	MTIOC4B/TMRI3/POE8#/RTCIC0	RXD1/SMISO1/SSCL1/ AUDIO_MCLK			IRQ0/CMPOB3
E4		P16	MTIOC3C/MTIOC3D/TMO2/ TIOCB1/TCLKC/RTCOUT	TXD1/SMOSI1/SSDA1/MOSIA/ SCL/USB0_VBUS/ USB0_VBUSEN/ USB0_OVRCURB			IRQ6/ADTRG0#
E5		PC4	MTIOC3D/MTCLKC/TMCI1/ POE0#	SCK5/CTS8#/RTS8#/SS8#/ SSLA0	SDHI_D1	TSCAP	
E6	VCC						
E7	VSS						
E8		PB0	MTIC5W/TIOCA3	RXD6/SMISO6/SSCL6/RSPCKA	SDHI_C MD		
F1	VCC						
F2	UPSEL	P35					NMI
F3		P31	MTIOC4D/TMCI2/RTCIC1	CTS1#/RTS1#/SS1#/SSISCK0			IRQ1

Table 1.9 List of Pins and Pin Functions (64-Pin LFQFP/HWQFN) (1/2)

Pin No.	Power Supply, Clock, System Control	I/O Port	Timers (MTU, TPU, TMR, RTC, CMT, POE, CAC)	Communications (SCI, RSPI, RIIC, RSCAN, USB, SSI)	Memory Interface (SDHI)	Touch sensing	Others
1		P03					DA0
2	VCL						
3	MD						FINED
4	XCIN						
5	XCOUT						
6	RES#						
7	XTAL	P37					
8	VSS						
9	EXTAL	P36					
10	VCC						
11	UPSEL	P35					NMI
12	VBATT						
13		P31	MTIOC4D/TMCI2/RTCIC1	CTS1#/RTS1#/SS1#/SSISCK0			IRQ1
14		P30	MTIOC4B/TMRI3/POE8#/RTCIC0	RXD1/SMISO1/SSCL1/ AUDIO_MCLK			IRQ0/CMPOB3
15		P27	MTIOC2B/TMCI3	SCK1/SSIWS0		TS2	CVREFB3
16		P26	MTIOC2A/TMO1	TXD1/SMOSI1/SSDA1/ USB0_VBUSEN/SSIRXD0		TS3	CMPB3
17		P17	MTIOC3A/MTIOC3B/TMO1/ POE8#/TIOCB0/TCLKD	SCK1/MISOA/SDA/SSITXD0			IRQ7/ CMPOB2
18		P16	MTIOC3C/MTIOC3D/TMO2/ TIOCB1/TCLKC/RTCOUT	TXD1/SMOSI1/SSDA1/MOSIA/ SCL/USB0_VBUS/ USB0_VBUSEN/ USB0_OVRCURB			IRQ6/ADTRG0#
19		P15	MTIOC0B/MTCLKB/TMCI2/ TIOCB2/TCLKB	RXD1/SMISO1/SSCL1/CRXD0		TS12	IRQ5/CMPB2
20		P14	MTIOC3A/MTCLKA/TMRI2/ TIOCB5/TCLKA	CTS1#/RTS1#/SS1#/CTXD0/ USB0_OVRCURA		TS13	IRQ4/CVREFB2
21	VCC_USB*1	PH3*1	TMCI0*1				
22		PH2*1	TMRI0*1	USB0_DM*1			IRQ1*1
23		PH1*1	TMO0*1	USB0_DP*1			IRQ0*1
24	VSS_USB*1	PH0*1					CACREF*1
25		P55	MTIOC4D/TMO3	CRXD0		TS15	
26		P54	MTIOC4B/TMCI1	CTXD0		TS16	
27	UB	PC7	MTIOC3A/MTCLKB/TMO2	TXD8/SMOSI8/SSDA8/MISOA			CACREF
28		PC6	MTIOC3C/MTCLKA/TMCI2	RXD8/SMISO8/SSCL8/MOSIA/ USB0_EXICEN		TS22	
29		PC5	MTIOC3B/MTCLKD/TMRI2	SCK8/RSPCKA/USB0_ID		TS23	
30		PC4	MTIOC3D/MTCLKC/TMCI1/ POE0#	SCK5/CTS8#/RTS8#/SS8#/ SSLA0	SDHI_D1	TSCAP	
31		PC3	MTIOC4D/TCLKB	TXD5/SMOSI5/SSDA5/ IRTXD5	SDHI_D0	TS27	
32		PC2	MTIOC4B/TCLKA	RXD5/SMISO5/SSCL5/SSLA3/ IRRXD5	SDHI_D3	TS30	
33		PB7/PC1	MTIOC3B/TIOCB5	TXD9/SMOSI9/SSDA9	SDHI_D2		
34		PB6/PC0	MTIOC3D/TIOCA5	RXD9/SMISO9/SSCL9	SDHI_D1		
35		PB5	MTIOC2A/MTIOC1B/TMRI1/ POE1#/TIOCB4	SCK9/USB0_VBUS	SDHI_CD		
36		PB3	MTIOC0A/MTIOC4A/TMO0/ POE3#/TIOCD3/TCLKD	SCK6	SDHI_WP		
37		PB1	MTIOC0C/MTIOC4C/TMCI0/ TIOCB3	TXD6/SMOSI6/SSDA6	SDHI_CLK		IRQ4/ CMPOB1
38	VCC						
39		PB0	MTIC5W/TIOCA3	RXD6/SMISO6/SSCL6/RSPCKA	SDHI_CMD		
40	VSS						
41		PA6	MTIC5V/MTCLKB/TMCI3/POE2#/ TIOCA2	CTS5#/RTS5#/SS5#/MOSIA/ SSIWS0			

2. CPU

Figure 2.1 shows register set of the CPU.



Note 1. The stack pointer (SP) can be the interrupt stack pointer (ISP) or user stack pointer (USP), according to the value of the U bit in the PSW.

Figure 2.1 Register Set of the CPU

Table 4.1 List of I/O Registers (Address Order) (26/33)

Address	Module Symbol	Register Name	Register Symbol	Number of Bits	Access Size	Number of Access Cycles	
						ICLK ≥ PCLK	ICLK <PCLK
000A 83DEh	RSCAN	Receive Rule Entry Register 5AH	GAFLIDH5	16	16	2 or 3 PCLKB	2 ICLK
000A 83DEh	RSCAN	Receive Buffer Register 3DH	RMDF33	16	16	2 or 3 PCLKB	2 ICLK
000A 83E0h	RSCAN	Receive Rule Entry Register 5BL	GAFLML5	16	16	2 or 3 PCLKB	2 ICLK
000A 83E0h	RSCAN	Receive Buffer Register 4AL	RMIDL4	16	16	2 or 3 PCLKB	2 ICLK
000A 83E2h	RSCAN	Receive Rule Entry Register 5BH	GAFLMH5	16	16	2 or 3 PCLKB	2 ICLK
000A 83E2h	RSCAN	Receive Buffer Register 4AH	RMIDH4	16	16	2 or 3 PCLKB	2 ICLK
000A 83E4h	RSCAN	Receive Rule Entry Register 5CL	GAFLPL5	16	16	2 or 3 PCLKB	2 ICLK
000A 83E4h	RSCAN	Receive Buffer Register 4BL	RMTS4	16	16	2 or 3 PCLKB	2 ICLK
000A 83E6h	RSCAN	Receive Rule Entry Register 5CH	GAFLPH5	16	16	2 or 3 PCLKB	2 ICLK
000A 83E6h	RSCAN	Receive Buffer Register 4BH	RMPTR4	16	16	2 or 3 PCLKB	2 ICLK
000A 83E8h	RSCAN	Receive Rule Entry Register 6AL	GAFLIDL6	16	16	2 or 3 PCLKB	2 ICLK
000A 83E8h	RSCAN	Receive Buffer Register 4CL	RMDF04	16	16	2 or 3 PCLKB	2 ICLK
000A 83EAh	RSCAN	Receive Rule Entry Register 6AH	GAFLIDH6	16	16	2 or 3 PCLKB	2 ICLK
000A 83EAh	RSCAN	Receive Buffer Register 4CH	RMDF14	16	16	2 or 3 PCLKB	2 ICLK
000A 83ECh	RSCAN	Receive Rule Entry Register 6BL	GAFLML6	16	16	2 or 3 PCLKB	2 ICLK
000A 83ECh	RSCAN	Receive Buffer Register 4DL	RMDF24	16	16	2 or 3 PCLKB	2 ICLK
000A 83EEh	RSCAN	Receive Rule Entry Register 6BH	GAFLMH6	16	16	2 or 3 PCLKB	2 ICLK
000A 83EEh	RSCAN	Receive Buffer Register 4DH	RMDF34	16	16	2 or 3 PCLKB	2 ICLK
000A 83F0h	RSCAN	Receive Rule Entry Register 6CL	GAFLPL6	16	16	2 or 3 PCLKB	2 ICLK
000A 83F0h	RSCAN	Receive Buffer Register 5AL	RMIDL5	16	16	2 or 3 PCLKB	2 ICLK
000A 83F2h	RSCAN	Receive Rule Entry Register 6CH	GAFLPH6	16	16	2 or 3 PCLKB	2 ICLK
000A 83F2h	RSCAN	Receive Buffer Register 5AH	RMIDH5	16	16	2 or 3 PCLKB	2 ICLK
000A 83F4h	RSCAN	Receive Rule Entry Register 7AL	GAFLIDL7	16	16	2 or 3 PCLKB	2 ICLK
000A 83F4h	RSCAN	Receive Buffer Register 5BL	RMTS5	16	16	2 or 3 PCLKB	2 ICLK
000A 83F6h	RSCAN	Receive Rule Entry Register 7AH	GAFLIDH7	16	16	2 or 3 PCLKB	2 ICLK
000A 83F6h	RSCAN	Receive Buffer Register 5BH	RMPTR5	16	16	2 or 3 PCLKB	2 ICLK
000A 83F8h	RSCAN	Receive Rule Entry Register 7BL	GAFLML7	16	16	2 or 3 PCLKB	2 ICLK
000A 83F8h	RSCAN	Receive Buffer Register 5CL	RMDF05	16	16	2 or 3 PCLKB	2 ICLK
000A 83FAh	RSCAN	Receive Rule Entry Register 7BH	GAFLMH7	16	16	2 or 3 PCLKB	2 ICLK
000A 83FAh	RSCAN	Receive Buffer Register 5CH	RMDF15	16	16	2 or 3 PCLKB	2 ICLK
000A 83FCh	RSCAN	Receive Rule Entry Register 7CL	GAFLPL7	16	16	2 or 3 PCLKB	2 ICLK
000A 83FCh	RSCAN	Receive Buffer Register 5DL	RMDF25	16	16	2 or 3 PCLKB	2 ICLK
000A 83FEh	RSCAN	Receive Rule Entry Register 7CH	GAFLPH7	16	16	2 or 3 PCLKB	2 ICLK
000A 83FEh	RSCAN	Receive Buffer Register 5DH	RMDF35	16	16	2 or 3 PCLKB	2 ICLK
000A 8400h	RSCAN	Receive Rule Entry Register 8AL	GAFLIDL8	16	16	2 or 3 PCLKB	2 ICLK
000A 8400h	RSCAN	Receive Buffer Register 6AL	RMIDL6	16	16	2 or 3 PCLKB	2 ICLK
000A 8402h	RSCAN	Receive Rule Entry Register 8AH	GAFLIDH8	16	16	2 or 3 PCLKB	2 ICLK
000A 8402h	RSCAN	Receive Buffer Register 6AH	RMIDH6	16	16	2 or 3 PCLKB	2 ICLK
000A 8404h	RSCAN	Receive Rule Entry Register 8BL	GAFLML8	16	16	2 or 3 PCLKB	2 ICLK
000A 8404h	RSCAN	Receive Buffer Register 6BL	RMTS6	16	16	2 or 3 PCLKB	2 ICLK
000A 8406h	RSCAN	Receive Rule Entry Register 8BH	GAFLMH8	16	16	2 or 3 PCLKB	2 ICLK
000A 8406h	RSCAN	Receive Buffer Register 6BH	RMPTR6	16	16	2 or 3 PCLKB	2 ICLK
000A 8408h	RSCAN	Receive Rule Entry Register 8CL	GAFLPL8	16	16	2 or 3 PCLKB	2 ICLK
000A 8408h	RSCAN	Receive Buffer Register 6CL	RMDF06	16	16	2 or 3 PCLKB	2 ICLK
000A 840Ah	RSCAN	Receive Rule Entry Register 8CH	GAFLPH8	16	16	2 or 3 PCLKB	2 ICLK
000A 840Ah	RSCAN	Receive Buffer Register 6CH	RMDF16	16	16	2 or 3 PCLKB	2 ICLK
000A 840Ch	RSCAN	Receive Rule Entry Register 9AL	GAFLIDL9	16	16	2 or 3 PCLKB	2 ICLK
000A 840Ch	RSCAN	Receive Buffer Register 6DL	RMDF26	16	16	2 or 3 PCLKB	2 ICLK
000A 840Eh	RSCAN	Receive Rule Entry Register 9AH	GAFLIDH9	16	16	2 or 3 PCLKB	2 ICLK
000A 840Eh	RSCAN	Receive Buffer Register 6DH	RMDF36	16	16	2 or 3 PCLKB	2 ICLK
000A 8410h	RSCAN	Receive Rule Entry Register 9BL	GAFLML9	16	16	2 or 3 PCLKB	2 ICLK
000A 8410h	RSCAN	Receive Buffer Register 7AL	RMIDL7	16	16	2 or 3 PCLKB	2 ICLK

Item					Symbol	Typ. *4	Max.	Unit	Test Conditions
Supply current	Middle-speed operating mode	Normal operating mode	All peripheral operation: Max.*7	ICLK = 12 MHz	I_{CC}	—	16.7	mA	
		Sleep mode	No peripheral operation*6	ICLK = 12 MHz		1.9	—		
				ICLK = 8 MHz		1.2	—		
				ICLK = 4 MHz		1.1	—		
				ICLK = 1 MHz		1.0	—		
			All peripheral operation: Normal*7	ICLK = 12 MHz		6.1	—		
				ICLK = 8 MHz		4.4	—		
				ICLK = 4 MHz		3.0	—		
				ICLK = 1 MHz		2.0	—		
		Deep sleep mode	No peripheral operation*6	ICLK = 12 MHz		1.6	—		
				ICLK = 8 MHz		1.0	—		
				ICLK = 4 MHz		0.9	—		
				ICLK = 1 MHz		0.8	—		
			All peripheral operation: Normal*7	ICLK = 12 MHz		5.1	—		
				ICLK = 8 MHz		3.7	—		
				ICLK = 4 MHz		2.6	—		
				ICLK = 1 MHz		1.8	—		
		Increase during BGO operation*5				2.5	—		
	Low-speed operating mode	Normal operating mode	No peripheral operation*8	ICLK = 32 kHz	I_{CC}	5.2	—	μA	
			All peripheral operation: Normal *9, *10	ICLK = 32 kHz		22.3	—		
			All peripheral operation: Max.*9, *10	ICLK = 32 kHz		—	74.4		
		Sleep mode	No peripheral operation*8	ICLK = 32 kHz		3.0	—		
			All peripheral operation: Normal*9	ICLK = 32 kHz		13.1	—		
		Deep sleep mode	No peripheral operation*8	ICLK = 32 kHz		2.4	—		
			All peripheral operation: Normal*9	ICLK = 32 kHz		10.5	—		

Note 1. Supply current values do not include the output charge/discharge current from all pins. The values apply when internal pull-up MOSs are in the off state.
Note 2. Clock supply to the peripheral functions is stopped. This does not include BGO operation. The clock source is PLL. BCLK, FCLK, and PCLK are set to divided by 64.
Note 3. Clocks are supplied to the peripheral functions. This does not include BGO operation. The clock source is PLL. BCLK, FCLK, and PCLK are the same frequency as that of ICLK.
Note 4. Values when VCC is 3.3 V.
Note 5. This is the increase when data is programmed to or erased from the ROM or E2 DataFlash during program execution.
Note 6. Clock supply to the peripheral functions is stopped. The clock source is PLL when ICLK is 12 MHz and HOCO for other cases. BCLK, FCLK, and PCLK are set to divided by 64.
Note 7. Clocks are supplied to the peripheral functions. The clock source is PLL when ICLK is 12 MHz and HOCO for other cases. BCLK, FCLK, and PCLK are the same frequency of that of the ICLK.
Note 8. Clock supply to the peripheral functions is stopped. The clock source is the sub oscillation circuit. BCLK, FCLK, and PCLK are set to divided by 64.
Note 9. Clocks are supplied to the peripheral functions. The clock source is the sub oscillation circuit. BCLK, FCLK, and PCLK are the same frequency as that of ICLK.
Note 10. This is the value when the MSTPCRA.MSTPA17 (12-bit A/D converter module stop bit) is in the module stop state.
Note 11. Clocks are supplied to the peripheral functions. This does not include BGO operation. The clock source is PLL. BCLK, FCLK, and PCLKB are set to divided by 2 and PCLKA and PCLKD are the same frequency as that of ICLK.

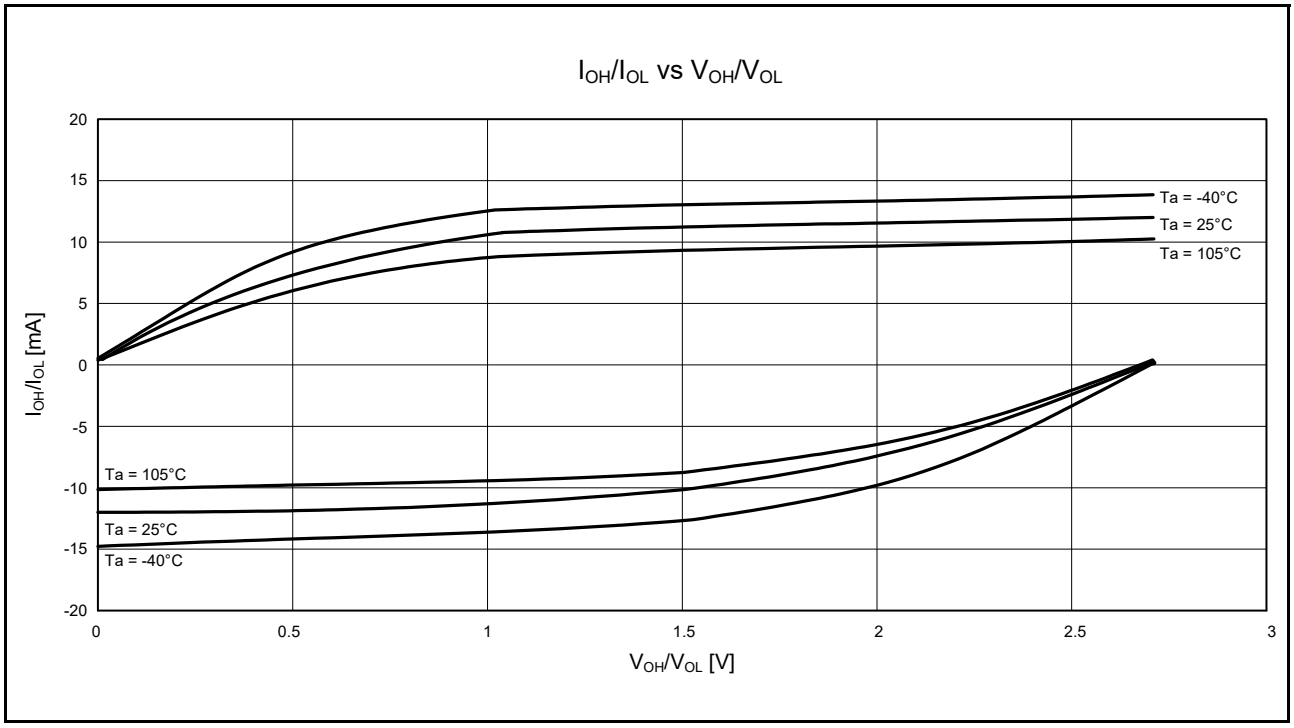


Figure 5.10 V_{OH}/V_{OL} and I_{OH}/I_{OL} Temperature Characteristics at VCC = 2.7 V When Normal Output is Selected (Reference Data)

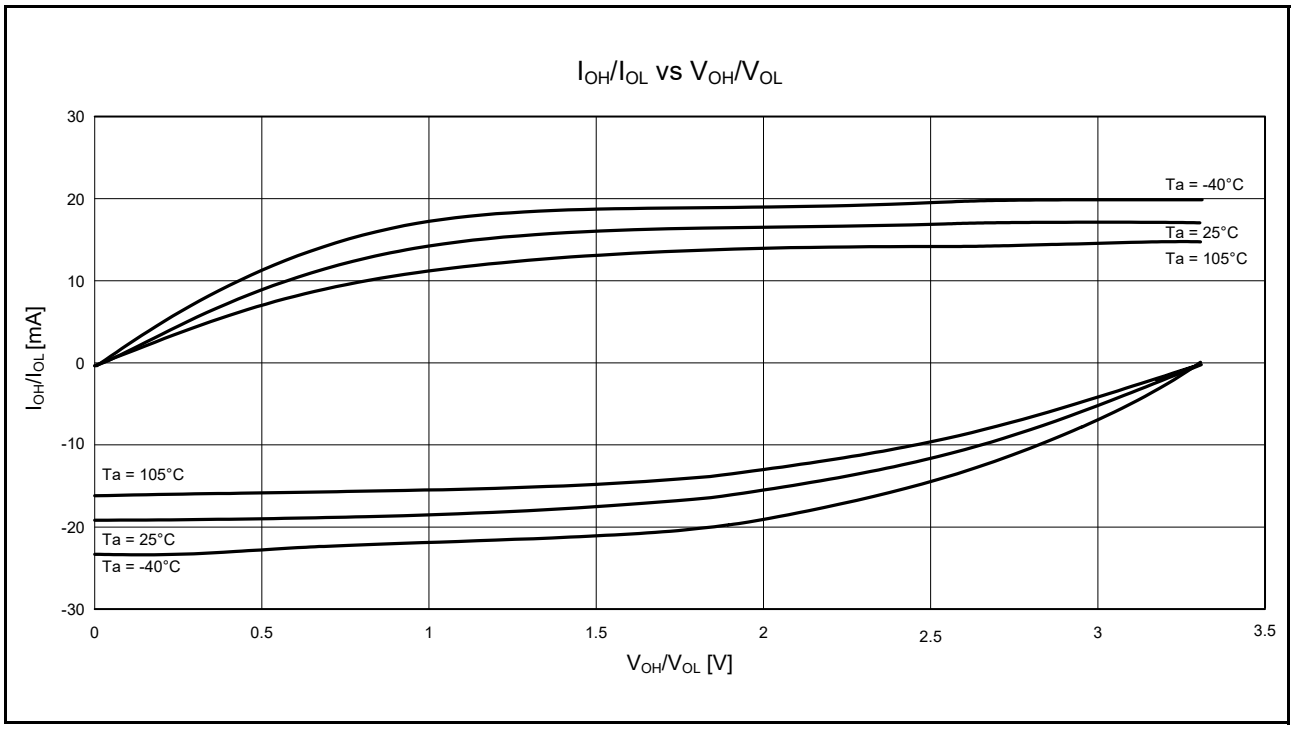


Figure 5.11 V_{OH}/V_{OL} and I_{OH}/I_{OL} Temperature Characteristics at VCC = 3.3 V When Normal Output is Selected (Reference Data)

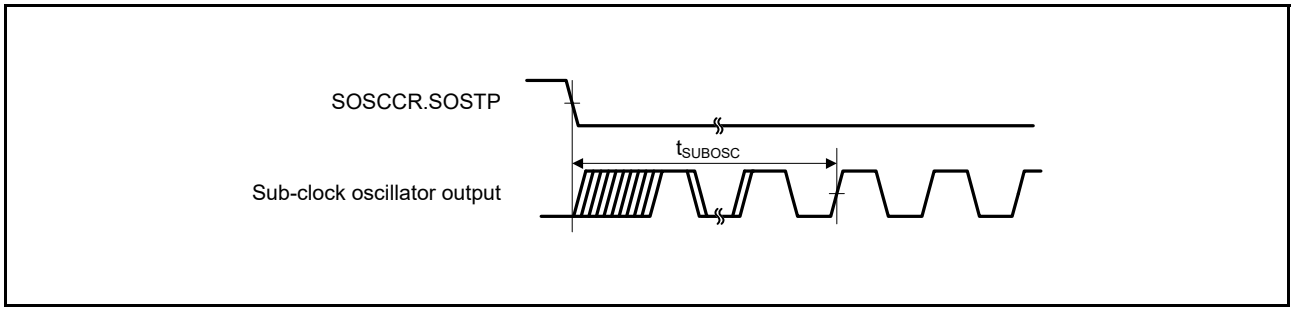


Figure 5.30 Sub-Clock Oscillation Start Timing

5.3.2 Reset Timing

Table 5.27 Reset Timing

Conditions: 1.8 V ≤ VCC = VCC_USB = AVCC0 ≤ 5.5 V, VSS = AVSS0 = VREFL0 = VSS_USB = 0 V, T_a = –40 to +105°C

Item		Symbol	Min.	Typ.	Max.	Unit	Test Conditions
RES# pulse width	At power-on	t_{RESWP}	3	—	—	ms	Figure 5.31
	Other than above	t_{RESW}	30	—	—	µs	Figure 5.32
Wait time after RES# cancellation (at power-on)	At normal startup*1	t_{RESWT}	—	8.5	—	ms	Figure 5.31
	During fast startup time*2	t_{RESWT}	—	560	—	µs	
Wait time after RES# cancellation (during powered-on state)		t_{RESWT}	—	120	—	µs	Figure 5.32
Independent watchdog timer reset period		t_{RESWIW}	—	1	—	IWDT clock cycle	Figure 5.33
Watchdog timer reset period		t_{RESWWW}	—	4	—	PCLKB cycle	
Software reset period		t_{RESWSW}	—	1	—	ICLK cycle	
Wait time after independent watchdog timer reset cancellation*3		t_{RESWT2}	—	300	—	µs	
Wait time after watchdog timer reset cancellation*4		t_{RESWT2}	—	300	—	µs	
Wait time after software reset cancellation		t_{RESWT2}	—	170	—	µs	

Note 1. When OFS1.(LVDAS, FASTSTUP) bits are 11b.
Note 2. When OFS1.(LVDAS, FASTSTUP) bits are a value other than 11b.
Note 3. When IWDTCR.CKS[3:0] bits are 0000b.
Note 4. When WDTCR.CKS[3:0] bits are 0001b.

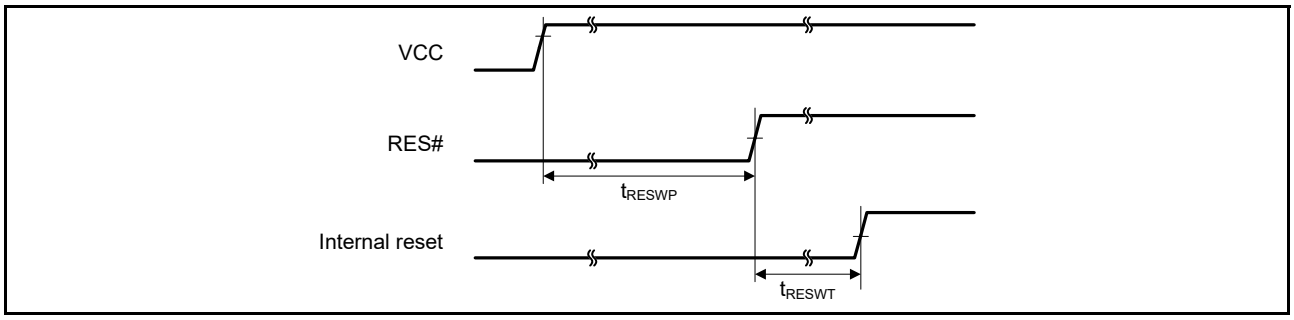


Figure 5.31 Reset Input Timing at Power-On

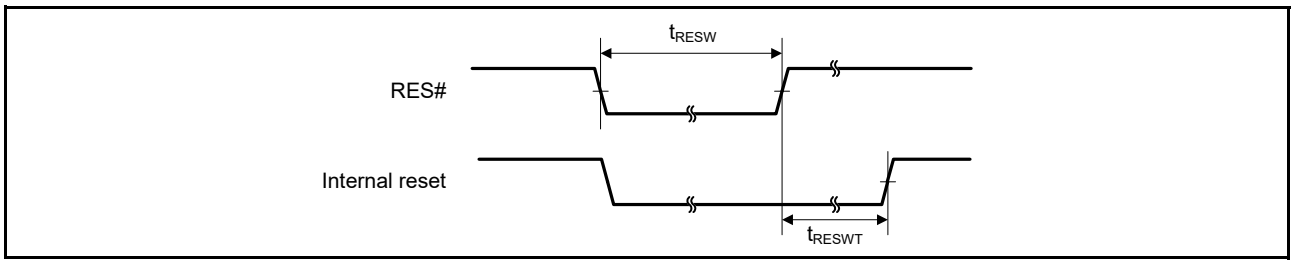


Figure 5.32 Reset Input Timing (1)

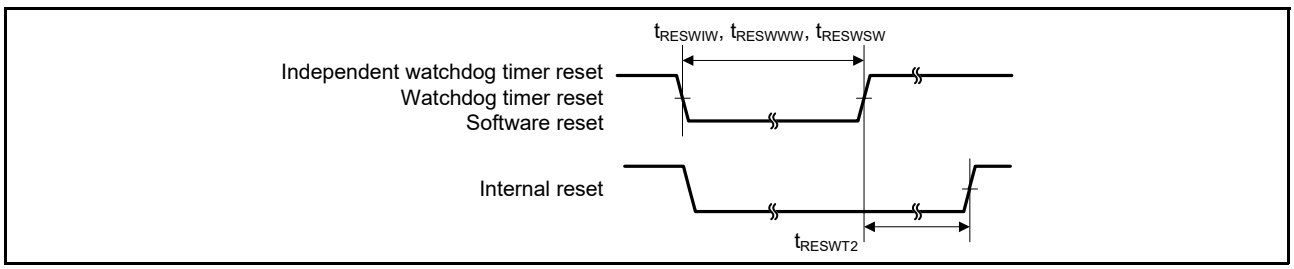


Figure 5.33 Reset Input Timing (2)

5.3.6 Timing of On-Chip Peripheral Modules

Table 5.38 Timing of On-Chip Peripheral Modules (1)

Conditions: 1.8 V ≤ VCC = VCC_USB = AVCC0 ≤ 5.5 V, VSS = AVSS0 = VSS_USB = 0 V, T_a = –40 to +105°C

Item			Symbol	Min.	Max.	Unit *1	Test Conditions
I/O ports	Input data pulse width		t_{PRW}	1.5	—	t_{Pcyc}	Figure 5.45
MTU2/TPU	Input capture input pulse width	Single-edge setting	t_{TICW}	1.5	—	t_{Pcyc}	Figure 5.46
		Both-edge setting		2.5	—		
	Timer clock pulse width	Single-edge setting	t_{TCKWH}, t_{TCKWL}	1.5	—	t_{Pcyc}	Figure 5.47
		Both-edge setting		2.5	—		
		Phase counting mode		2.5	—		
POE2	POE# input pulse width		t_{POEW}	1.5	—	t_{Pcyc}	Figure 5.48
TMR	Timer clock pulse width	Single-edge setting	t_{TMCWH}, t_{TMCWL}	1.5	—	t_{Pcyc}	Figure 5.49
		Both-edge setting		2.5	—		
SCI	Input clock cycle time	Asynchronous	t_{Scyc}	4	—	t_{Pcyc}	Figure 5.50
		Clock synchronous		6	—		
	Input clock pulse width		t_{SCKW}	0.4	0.6	t_{Scyc}	
	Input clock rise time		t_{SCKr}	—	20	ns	
	Input clock fall time		t_{SCKf}	—	20	ns	
	Output clock cycle time	Asynchronous	t_{Scyc}	16	—	t_{Pcyc}	Figure 5.51
		Clock synchronous		4	—		
	Output clock pulse width		t_{SCKW}	0.4	0.6	t_{Scyc}	
	Output clock rise time		t_{SCKr}	—	20	ns	
	Output clock fall time		t_{SCKf}	—	20	ns	
	Transmit data delay time (master)	Clock synchronous	t_{TXD}	—	40	ns	
	Transmit data delay time (slave)	Clock synchronous, 2.7 V or above		—	65	ns	
		Clock synchronous, 1.8 V or above		—	100	ns	
	Receive data setup time (master)	Clock synchronous, 2.7 V or above	t_{RXS}	65	—	ns	
		Clock synchronous, 1.8 V or above		90	—	ns	
	Receive data setup time (slave)	Clock synchronous		40	—	ns	
	Receive data hold time	Clock synchronous	t_{RXH}	40	—	ns	
A/D converter	Trigger input pulse width		t_{TRGW}	1.5	—	t_{Pcyc}	Figure 5.52
CAC	CACREF input pulse width	$t_{Pcyc} \le t_{cac}$ *2	t_{CACREF}	4.5 t_{cac} + 3 t_{Pcyc}	—	ns	
		$t_{Pcyc} > t_{cac}$ *2		5 t_{cac} + 6.5 t_{Pcyc}			
CLKOUT	CLKOUT pin output cycle*4	VCC = 2.7 V or above	t_{Ccyc}	62.5	—	ns	Figure 5.53
		VCC = 1.8 V or above		125			
	CLKOUT pin high pulse width*3	VCC = 2.7 V or above	t_{CH}	15	—	ns	
		VCC = 1.8 V or above		30			
	CLKOUT pin low pulse width*3	VCC = 2.7 V or above	t_{CL}	15	—	ns	
		VCC = 1.8 V or above		30			
	CLKOUT pin output rise time	VCC = 2.7 V or above	t_{Cr}	—	12	ns	
		VCC = 1.8 V or above			25		
	CLKOUT pin output fall time	VCC = 2.7 V or above	t_{Cf}	—	12	ns	
		VCC = 1.8 V or above			25		

Note 1. t_{Pcyc}: PCLK cycle
Note 2. t_{cac}: CAC count clock source cycle
Note 3. When the LOCO is selected as the clock output source (the CKOCR.CKOSEL[2:0] bits are 000b), set the clock output division ratio selection to divided by 2 (the CKOCR.CKODIV[2:0] bits are 001b).
Note 4. When the EXTAL external clock input or an oscillator is used with divided by 1 (the CKOCR.CKOSEL[2:0] bits are 010b and the CKOCR.CKODIV[2:0] bits are 000b) to output from CLKOUT, the above should be satisfied with an input duty cycle of 45 to 55%.

Table 5.42 Timing of On-Chip Peripheral Modules (5)

Conditions: 2.7 V ≤ VCC = VCC_USB = AVCC0 ≤ 5.5 V, VSS = AVSS0 = VSS_USB = 0 V, fPCLKB ≤ 32 MHz,
T_a = –40 to +105°C

Item		Symbol	Min.*1	Max.	Unit	Test Conditions
Simple I²C (Standard mode)	SDA rise time	t_{Sr}	—	1000	ns	Figure 5.59
	SDA fall time	t_{Sf}	—	300	ns	
	SDA spike pulse removal time	t_{SP}	0	4 × t_{Pcyc}	ns	
	Data setup time	t_{SDAS}	250	—	ns	
	Data hold time	t_{SDAH}	0	—	ns	
	SCL, SDA capacitive load	C_b	—	400	pF	
Simple I²C (Fast mode)	SDA rise time	t_{Sr}	—	300	ns	Figure 5.59
	SDA fall time	t_{Sf}	—	300	ns	
	SDA spike pulse removal time	t_{SP}	0	4 × t_{Pcyc}	ns	
	Data setup time	t_{SDAS}	100	—	ns	
	Data hold time	t_{SDAH}	0	—	ns	
	SCL, SDA capacitive load	C_b	—	400	pF	

Note: t_{Pcyc}: PCLK cycle
Note 1. C_b is the total capacitance of the bus lines.

Table 5.43 Timing of On-Chip Peripheral Modules (6)

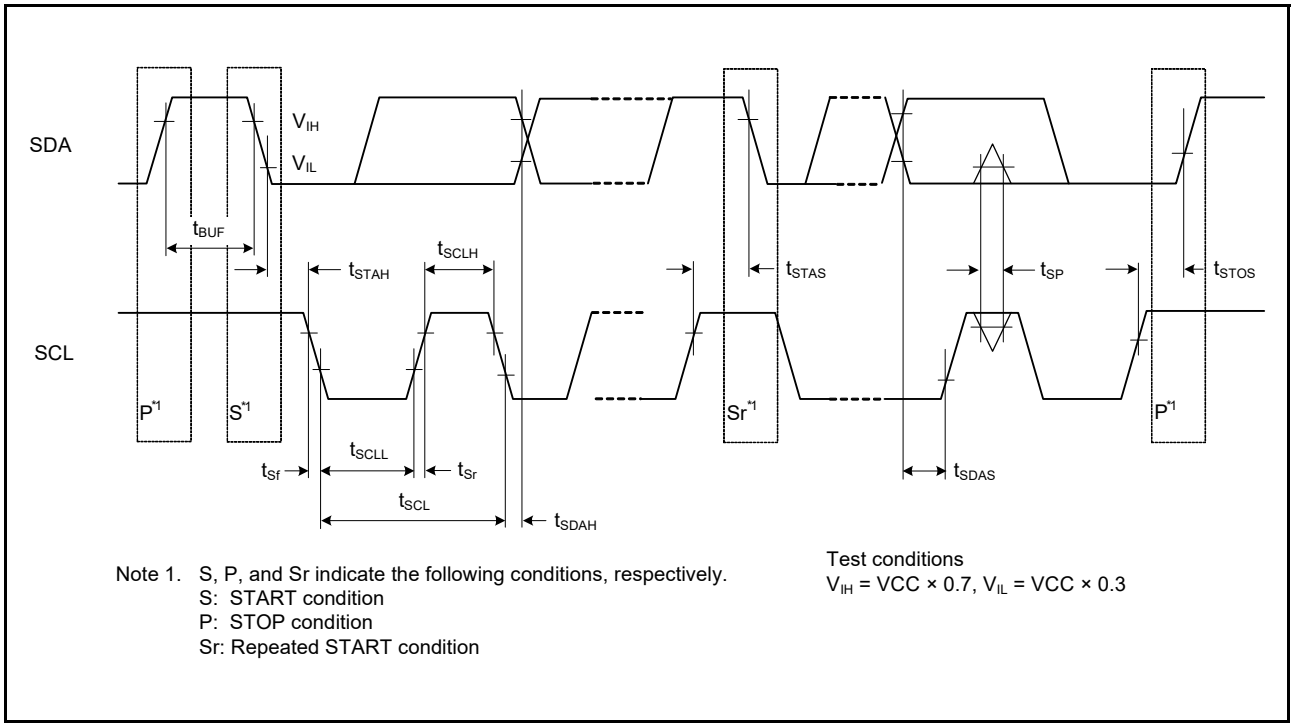
Conditions: 1.8 V ≤ VCC = VCC_USB = AVCC0 ≤ 5.5 V, VSS = AVSS0 = VSS_USB = 0 V, fPCLKB ≤ 32 MHz,
T_a = –40 to +105°C

Item			Symbol	Min.	Max.	Unit	Test Conditions
SSI	AUDIO_MCLK input frequency	2.7 V or above	t_{AUDIO}	1	25	MHz	
		1.8 V or above		1	4		
	Output clock cycle		t_O	250	—	ns	Figure 5.60
	Input clock cycle		t_I	250	—	ns	
	Clock high level		t_{HC}	0.4	0.6	to, ti	
	Clock low level		t_{LC}	0.4	0.6	to, ti	
	Clock rise time		t_{RC}	—	20	ns	
	Data delay time	2.7 V or above	t_{DTR}	—	65	ns	Figure 5.61 Figure 5.62
		1.8 V or above		—	105		
	Setup time	2.7 V or above	t_{SR}	65	—	ns	
		1.8 V or above		90	—		
	Hold time		t_{HTR}	40	—	ns	
	WS changing edge SSIDATA output delay		t_{DTRW}	—	105	ns	Figure 5.63

Table 5.44 Timing of On-Chip Peripheral Modules (7)

Conditions: 2.7 V ≤ VCC = VCC_USB = AVCC0 ≤ 3.6 V, VSS = AVSS0 = VSS_USB = 0 V, fPCLKB ≤ 32 MHz,
T_a = –40 to +105°C,
when high-drive output is selected by the drive capacity control register

Item		Symbol	Min.	Max.	Unit	Test Conditions
SDHI	SDHI_CLK pin output cycle time	$t_{PP(SD)}$	62.5	—	ns	Figure 5.64
	SDHI_CLK pin output high pulse width	$t_{WH(SD)}$	18.25	—	ns	
	SDHI_CLK pin output low pulse width	$t_{WL(SD)}$	18.25	—	ns	
	SDHI_CLK pin output rise time	$t_{TLH(SD)}$	—	10	ns	
	SDHI_CLK pin output fall time	$t_{THL(SD)}$	—	10	ns	
	Output data delay time (data transfer mode) for SDHI_CMD and SDHI_D0 to SDHI_D3 pins	$t_{ODLY(SD)}$	–18.25	18.25	ns	
	Input data setup time for SDHI_CMD and SDHI_D0 to SDHI_D3 pins	$t_{ISU(SD)}$	9.25	—	ns	
	Input data hold time for SDHI_CMD and SDHI_D0 to SDHI_D3 pins	$t_{IH(SD)}$	8.3	—	ns	



Note 1. S, P, and Sr indicate the following conditions, respectively.
S: START condition
P: STOP condition
Sr: Repeated START condition

Figure 5.59 RIIC Bus Interface Input/Output Timing and Simple I²C Bus Interface Input/Output Timing

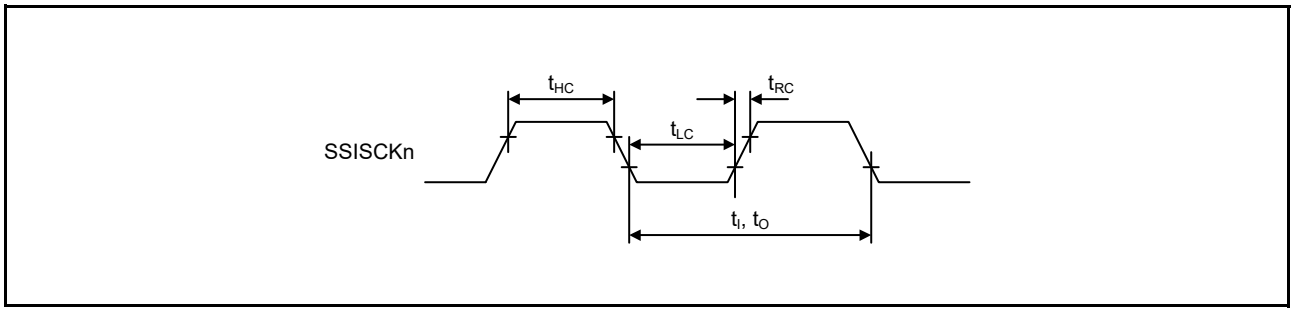


Figure 5.60 SSI Clock Input/Output Timing

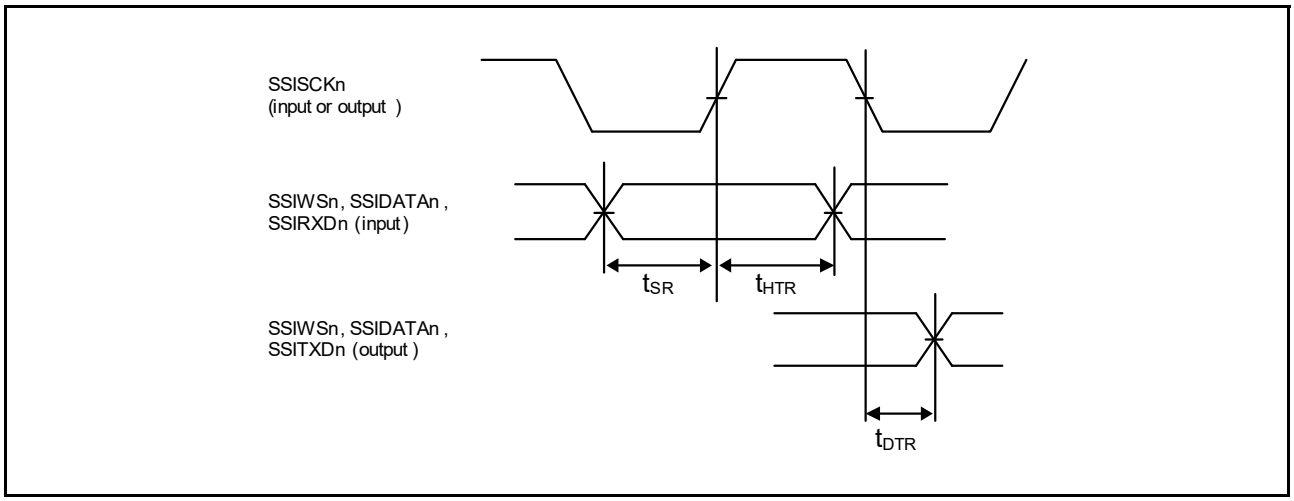


Figure 5.61 SSI Transmission/Reception Timing (SSICR.SCKP=0)

Table 5.50 A/D Conversion Characteristics (5)

Conditions: 1.8V ≤ VCC = VCC_USB = AVCC0 ≤ 5.5V, 1.8V ≤ VREFH0 ≤ AVCC0, VSS = AVSS0 = VSS_USB = 0V, reference voltage = VREFH0 selected, Ta = –40 to +105°C

Item		Min.	Typ.	Max.	Unit	Test Conditions
Frequency		1	—	8	MHz	
Resolution		—	—	12	Bit	
Conversion time*1 (Operation at PCLKD = 8 MHz)	Permissible signal source impedance (Max.) = 5 kΩ	6.75	—	—	µs	High-precision channel The ADCSR.ADHSC bit is 1 The ADSSTRn register is 0Dh
		10.13	—	—		Normal-precision channel The ADCSR.ADHSC bit is 1 The ADSSTRn register is 28h
Analog input capacitance	Cs	—	—	15	pF	Pin capacitance included Figure 5.68
Analog input resistance	Rs	—	—	2.5	kΩ	Figure 5.68
Offset error		—	±1	±7.5	LSB	
Full-scale error		—	±1.5	±7.5	LSB	
Quantization error		—	±0.5	—	LSB	
Absolute accuracy		—	±3.0	±8.0	LSB	
DNL differential non-linearity error		—	±1.0	—	LSB	
INL integral non-linearity error		—	±1.25	±3.0	LSB	

Note: The characteristics apply when no pin functions other than A/D converter input are used. Absolute accuracy includes quantization errors. Offset error, full-scale error, DNL differential non-linearity error, and INL integral non-linearity error do not include quantization errors.

Note 1. The conversion time is the sum of the sampling time and the comparison time. As the test conditions, the number of sampling states is indicated.

Table 5.51 A/D Converter Channel Classification

Classification	Channel	Conditions	Remarks
High-precision channel	AN000 to AN007	AVCC0 = 1.8 to 5.5 V	Pins AN000 to AN007 cannot be used as digital outputs when the A/D converter is in use.
Normal-precision channel	AN016 to AN031		
Internal reference voltage input channel	Internal reference voltage	AVCC0 = 2.0 to 5.5 V	
Temperature sensor input channel	Temperature sensor output	AVCC0 = 2.0 to 5.5 V	

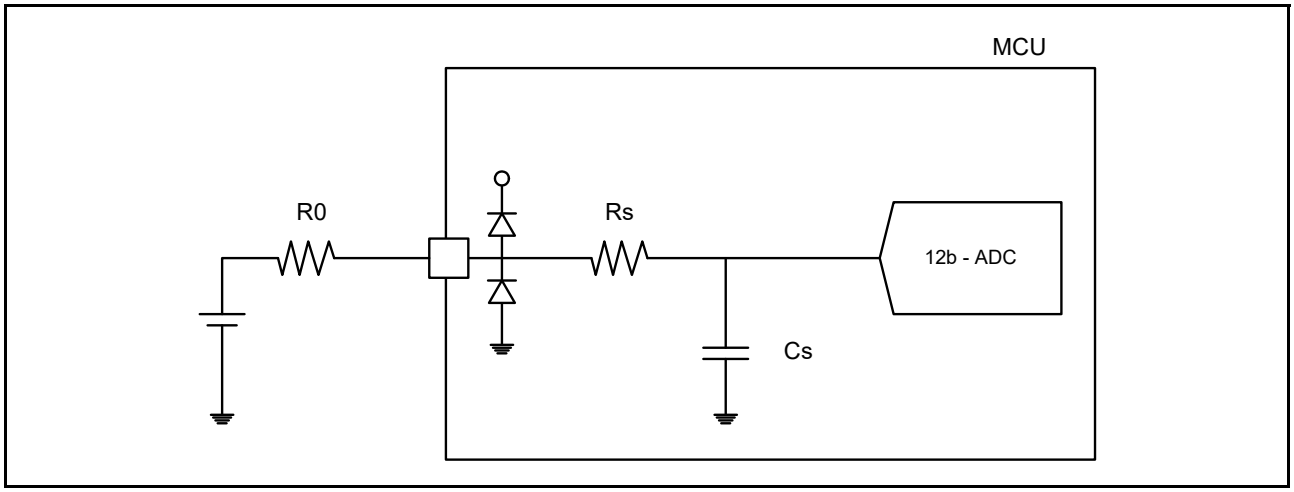


Figure 5.68 Equivalent Circuit

5.13 ROM (Flash Memory for Code Storage) Characteristics

Table 5.62 ROM (Flash Memory for Code Storage) Characteristics (1)

Item		Symbol	Min.	Typ.	Max.	Unit	Conditions
Reprogramming/erasure cycle*1		N_{PEC}	1000	—	—	Times	
Data hold time	After 1000 times of N_{PEC}	t_{DRP}	20*2, *3	—	—	Year	T_a = +85°C

Note 1. Definition of reprogram/erase cycle: The reprogram/erase cycle is the number of erasing for each block. When the reprogram/erase cycle is n times (n = 1000), erasing can be performed n times for each block. For instance, when 4-byte programming is performed 256 times for different addresses in a 1-Kbyte block and then the entire block is erased, the reprogram/erase cycle is counted as one. However, programming the same address for several times as one erasing is not enabled (overwriting is prohibited).
Note 2. Characteristic when using the flash memory programmer and the self-programming library provided from Renesas Electronics.
Note 3. This result is obtained from reliability testing.

Table 5.63 ROM (Flash Memory for Code Storage) Characteristics (2) High-Speed Operating Mode

Conditions: 2.7 V ≤ VCC = VCC_USB = AVCC0 ≤ 5.5 V, VSS = AVSS0 = VSS_USB = 0 V

Temperature range for the programming/erasure operation: T_a = –40 to +105°C

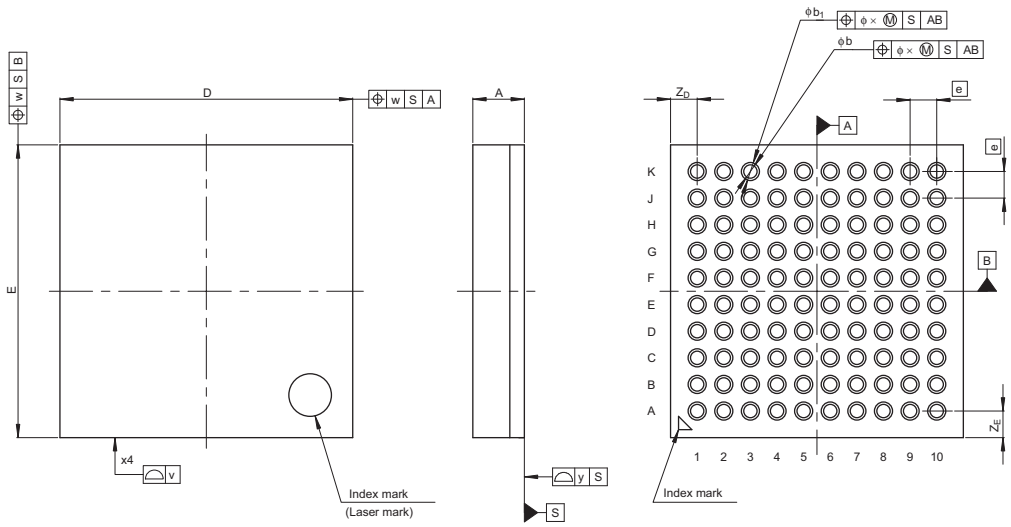
Item		Symbol	FCLK = 1 MHz			FCLK = 32 MHz			Unit
			Min.	Typ.	Max.	Min.	Typ.	Max.	
Programming time	8-byte	t_{P8}	—	112	967	—	52.3	491	µs
Erasure time	2-Kbyte	t_{E2K}	—	8.75	278	—	5.50	215	ms
	512-Kbyte (when block erase command is used)	t_{E512K}	—	928	19218	—	72.0	1679	ms
	512-Kbyte (when all-block erase command is used)	t_{EA512K}	—	923	19013	—	66.7	1469	ms
Blank check time	8-byte	t_{BC8}	—	—	55.0	—	—	16.1	µs
	2-Kbyte	t_{BC2K}	—	—	1840	—	—	136	ms
Erase operation forced stop time		t_{SED}	—	—	18.0	—	—	10.7	µs
Start-up area switching setting time		t_{SAS}	—	12.3	566.5	—	6.2	434	ms
Access window time		t_{AWS}	—	12.3	566.5	—	6.2	434	ms
ROM mode transition wait time 1		t_{DIS}	2.0	—	—	2.0	—	—	µs
ROM mode transition wait time 2		t_{MS}	5.0	—	—	5.0	—	—	µs

Note: The time until each operation of the flash memory is started after instructions are executed by software is not included.
Note: The lower-limit frequency of FCLK is 1 MHz during programming or erasing of the flash memory. When using FCLK at below 4 MHz, the frequency can be set to 1 MHz, 2 MHz, or 3 MHz. A non-integer frequency such as 1.5 MHz cannot be set.
Note: The frequency accuracy of FCLK must be within ±3.5%.

Appendix 1. Package Dimensions

Information on the latest version of the package dimensions or mountings has been displayed in “Packages” on Renesas Electronics Corporation website.

JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
P-TFLGA100-5.5x5.5-0.50	PTLG0100KA-A	100F0M	0.1g



Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	—	5.5	—
E	—	5.5	—
v	—	—	0.15
w	—	—	0.20
A	—	—	1.05
e	—	0.5	—
b	0.21	0.25	0.29
b_1	0.29	0.34	0.39
x	—	—	0.08
y	—	—	0.08
Z_D	—	0.5	—
Z_E	—	0.5	—

Figure A 100 -Pin TFLGA (PTLG0100KA-A)

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